Taiwan Semiconductor

0.8A, 200V - 1000V Standard Bridge Rectifier

FEATURES

TAIWAN

• AEC-Q101 qualified available

SEMICONDUCTOR

- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- UL Recognized File # E-326854
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application

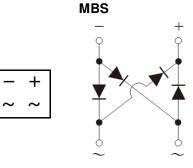
MECHANICAL DATA

- Case: TO-269AA (MBS)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.120g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
١ _F	0.8	А		
V _{RRM}	200 - 1000	V		
I _{FSM}	35	А		
T _{J MAX}	150	°C		
Package	TO-269AA (MBS)			
Configuration	Quad			







ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	MBS2	MBS4	MBS6	MBS8	MBS10	UNIT
Marking code on the device			MBS2	MBS4	MBS6	MBS8	MBS10	
Repetitive peak reverse voltage		V _{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current	On glass-epoxy	I	0.5			Α		
On aluminum substrate		I _F	0.8				Α	
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load		I _{FSM}	35				А	
Rating for fusing (t<8.3ms)		l ² t	5.08			A ² s		
Junction temperature		TJ	- 55 to +150				°C	
Storage temperature		T _{STG}	- 55 to +150					°C



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance ⁽¹⁾	R _{eJL}	20	°C/W	
Junction-to-ambient thermal resistance ⁽²⁾	R _{eja}	70	°C/W	
Junction-to-ambient thermal resistance ⁽¹⁾	R _{eja}	85	°C/W	

Notes:

- 1. On glass epoxy P.C.B. mounted on 0.05" x 0.05" (1.3mm x 1.3mm) pads
- On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20mm x 20mm) mounted on 0.05" x 0.05" (1.3mm x 1.3mm) solder pads

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 0.4A, T_J = 25^{\circ}C$	V _F	-	1	V
Reverse current @ rated V _R per diode ⁽²⁾	$T_J = 25^{\circ}C$	1	-	5	μA
Reverse current @ rated v _R per diode	T _J = 125°C	I _R	-	100	μA
Junction capacitance per diode	1MHz, V _R = 4.0 V	CJ	13	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾⁽²⁾	PACKAGE	PACKING		
MBSx	TO-269AA (MBS)	3,000 / Tape & Reel		
MBSxH	TO-269AA (MBS)	3,000 / Tape & Reel		

Notes:

- 1. "x" defines voltage from 200V(MBS2) to 1000V(MBS10)
- 2. "H" means AEC-Q101 qualified



100

10

1

0.1

0.01

10 20 30 40 50

INSTANTANEOUS REVERSE CURRENT (µA)

CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

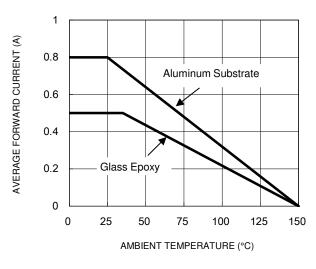


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

T_=125°C

T_J=25°C

PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

60 70

80 90

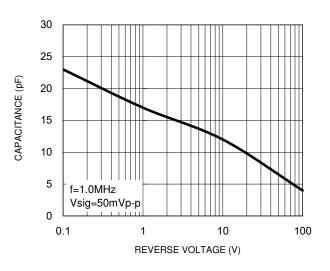
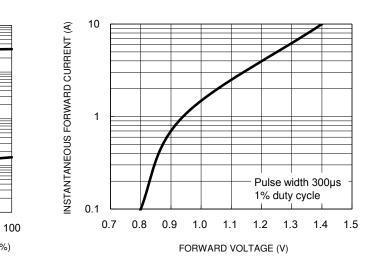


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



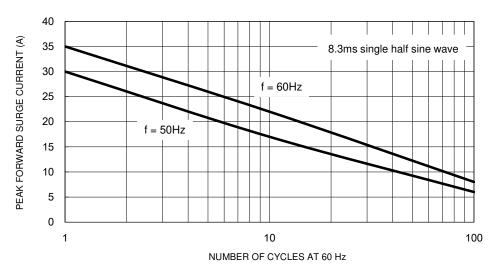
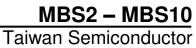
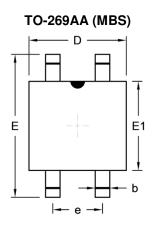


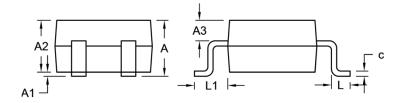
Fig.5 Maximum Non-Repetitive Forward Surge Current





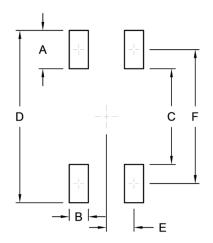
PACKAGE OUTLINE DIMENSIONS





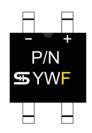
DIM.	Unit (mm)		Unit	(inch)	
	Min.	Max.	Min.	Max.	
A	-	2.90	-	0.114	
A1	-	0.20	-	0.008	
A2	2.30	2.70	0.091	0.106	
A3	0.95	1.53	0.037	0.060	
b	0.56	0.84	0.022	0.033	
с	0.15	0.35	0.006	0.014	
D	4.50	4.90	0.177	0.193	
E	-	6.90	-	0.272	
E1	3.60	5.00	0.142	0.197	
е	2.20	2.60	0.087	0.102	
L	0.70	1.10	0.028	0.043	
L1	1.10	2.12	0.043	0.083	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.80	0.071
В	0.90	0.035
С	4.50	0.177
D	8.10	0.319
E	1.30	0.051
F	6.30	0.248

MARKING DIAGRAM



- P/N = Marking Code
- YW = Date Code
- F = Factory Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.